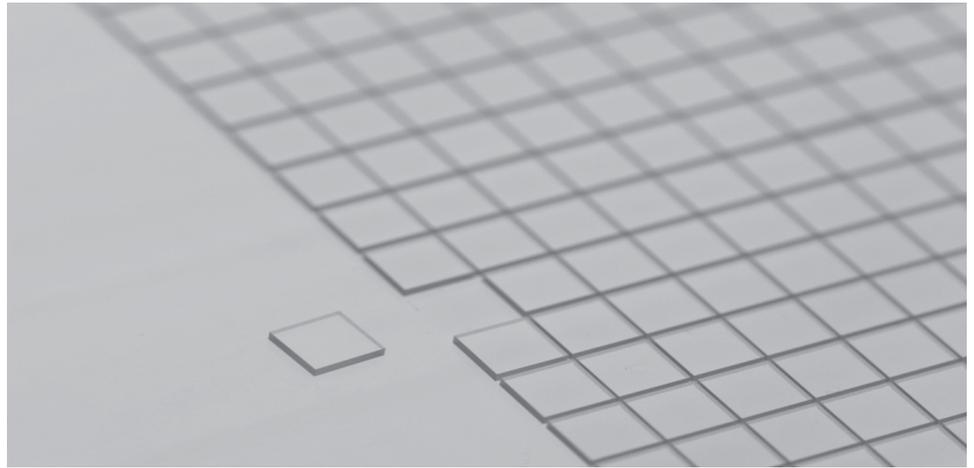


**CORNING**  
Laser Technologies



## Dynatex DTX-200 by CLT

### Glass Separation Processing with StreetSmart Breaker

For over 170 years, Corning has applied its unparalleled expertise in glass science, ceramic science, and optical physics. Now, Corning Laser Technologies (CLT) is leveraging 20-plus years of experience in precision laser machining with Dynatex International's 60 years expertise in die singulation.

The CLT 400S-WD is a dedicated tool for the nanoPerforation of glass wafers at unparalleled speed (up to 500 mm/s). CLT's unique nanoPerforation technology provides a modification trace through the entire thickness of glass (0.1 mm to 2.0 mm) in a single pass and allows for subsequent high-quality breaks with the DTX-200.

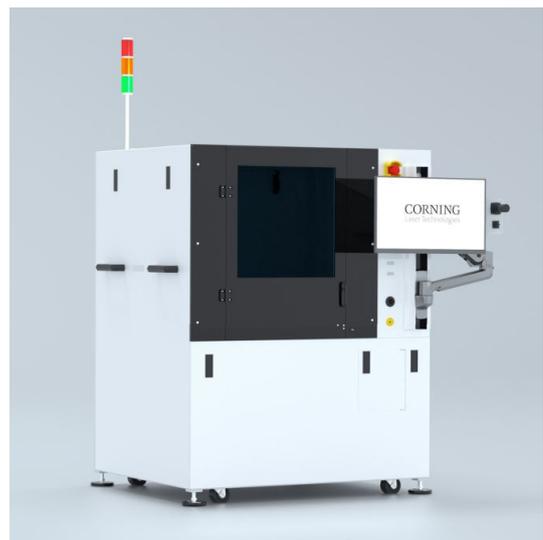
### Functionality:

#### **For high precision and high-volume production:**

- Maintain in-house control of glass device processing coated and non-coated glass by separating glass panels before or after applying a sensitive coating with no contact at the sensitive or active area of devices
- Provide consistent, repeatable process which yields high-volume production as demand increases

#### **For use in R&D and pilot production of glass-based biomedical devices:**

- Eliminate hand-breaking of glass which yields smooth, straight edges for more consistent results, reducing staff time to drive lower production cost and higher efficiency
- Produce highly scalable separation process which allows seamless switching between large-scale production and R&D



## Glass substrate material available:

- Borosilicate glass
- Fused silica
- Single & stacked glass

## Features:

- Fully Automatic processing; or Operator Driven processing
- Up to 200 mm Wafer, and Small Piece processing
- Interactive/Wizard mode for operator-controlled sequencing / processing
- Multiple Break Types/Assemblies available
- User friendly GUI with touch screen operation for ease of use
- Integrated Scribe and Break Stages available

## Applications:

- Wafer-based glass for semiconductor devices/optical systems
- RFICs
- Si-Photonics III-V chips
- Laser Diode Cleaving and Matrix Bar-to-Die separation
- OptoElectronics Devices (PhotoDiodes, Modulators, etc.)
- MEMS and BioMedical devices with sensitive structures/coatings
- LED separation (typically Break Only application)

## System Specifications:

Power Required	100/120 VAC 20 A or 220/240 VAC 10 A, 50/60 Hz
Environment	21° C +/- 6° C, 50% r.H. +/- 10% r.H. (non condensing)
Height	1,981 mm (78 inch)
Width	1,448 mm (57 inch)
Depth	1,270 mm (50 inch)
Capacity	up to 200 mm square or round wafer size
Break Time	~0.75 to 1.5 seconds per break

## CORNING Laser Technologies

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